







DUAL 40V PNP LOW SATURATION SWITCHING TRANSISTOR

Features and Benefits

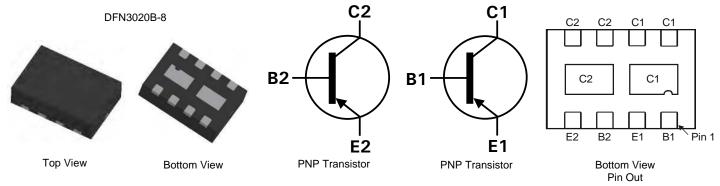
- BV_{CEO} > -40V
- I_C = -3A Continuous Collector Current
- Low Saturation Voltage (-220mV @ -1A)
- $R_{SAT} = 104 \text{ m}\Omega$ for Low Equivalent On Resistance
- hFE specified up to -3A for high gain holds up
- Dual NPN saving footprint and component count
- Low profile 0.8mm high package for thin applications
- R_{0JA} efficient, 40% lower than SOT26
- 6mm² footprint, 50% smaller than TSOP6 and SOT26
- Lead-Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free. "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: DFN3020B-8
- Case material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Terminals: Pre-Plated NiPdAu leadframe.
- Nominal package height: 0.8mm
- Moisture Sensitivity: Level 1 per J-STD-020
- Solderable per MIL-STD-202, Method 208
- Weight: 0.013 grams (approximate)

Applications

- DC-DC Converters
- Charging circuits
- Power switches
- Motor control
- CCFL Backlighting
- Portable applications



Equivalent Circuit

Ordering Information (Note 3)

_					
	Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
	ZXTD720MCTA	D33	7	8	3,000

Notes:

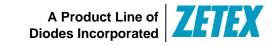
- 1. No purposefully added lead.
- 2. Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For Packaging Details, go to our website at http://www.diodes.com.

Marking Information

D33

D33 = Product type Marking Code Top View, Dot Denotes Pin 1





Maximum Ratings @ T_A = 25°C unless other wise specified

Parameter	Symbol	Limit	Unit	
Collector-Base Voltage	V_{CBO}	-50		
Collector-Emitter Voltage	V _{CEO}	-40	V	
Emitter-Base Voltage	V_{EBO}	-7		
Peak Pulse Current	I _{CM}	-4		
Continuous Collector Current (Notes 4 and 7)	Ic	-3	Α	
Base Current	I _B	-1		

Thermal Characteristics @ TA = 25° C unless otherwise specified

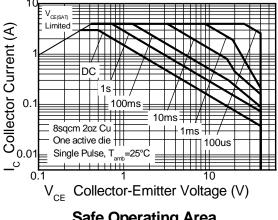
Characteristic	Symbol	Value	Unit		
	(Notes 4 & 7)		1.5 12		
Power Dissipation	(Notes 5 & 7)	_	2.45 19.6	W mW/°C	
Linear Derating Factor	(Notes 6 & 7)	P _D	1.13 8		
	(Notes 6 & 8)] [1.7 13.6		
	(Notes 4 & 7)		83.3		
Thermal Desistance Junation to Ambient	(Notes 5 & 7)		51.0		
Thermal Resistance, Junction to Ambient	(Notes 6 & 7)	$R_{\theta JA}$	111	°C/W	
	(Notes 6 & 8)		73.5		
Thermal Resistance, Junction to Lead	(Notes 7 & 9)	$R_{ heta JL}$	17.1		
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C		

Notes:

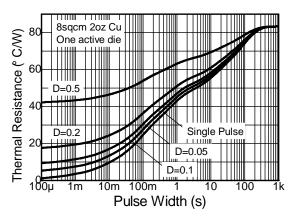
- 4. For a dual device surface mounted on 28mm x 28mm (8cm²) FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions; the device is measured when operating in a steady-state condition. The heatsink is split in half with the exposed collector pads connected to each half.
- 5. Same as note (4), except the device is measured at t <5 sec.
- 6. Same as note (4), except the device is surface mounted on 31mm x 31mm (10cm²) FR4 PCB with high coverage of single sided 1oz copper.
- 7. For a dual device with one active die.
- 8. For dual device with 2 active die running at equal power.
- 9. Thermal resistance from junction to solder-point (at the end of the collector lead).



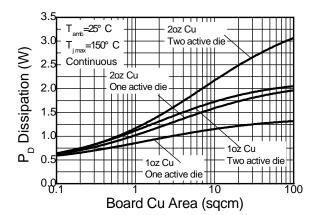
Thermal Characteristics



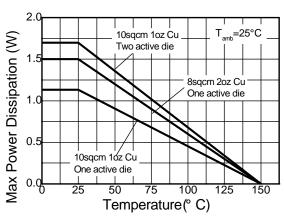
Safe Operating Area



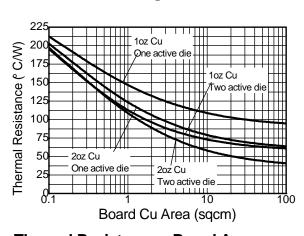
Transient Thermal Impedance



Power Dissipation v Board Area



Derating Curve



Thermal Resistance v Board Area





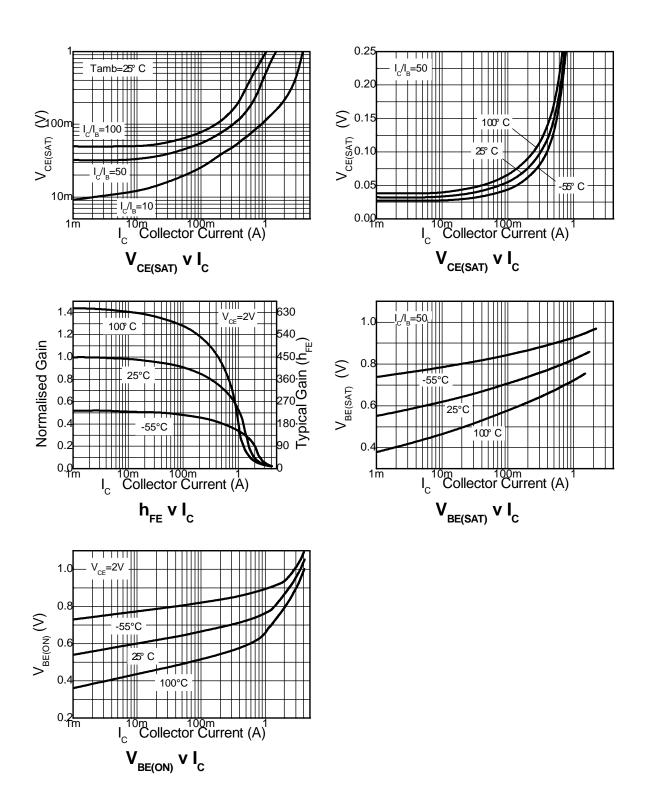
Electrical Characteristics @T_A = 25°C unless other wise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	-50	-80	-	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 10)	V _{(BR)CEO}	-40	-70	-	V	I _C = -10mA
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-7	-8.5	-	V	I _E = -100μA
Collector Cutoff Current	I _{CBO}	-	-	-100	nA	V _{CB} = -40V
Emitter Cutoff Current	I _{EBO}	-	-	-100	nA	V _{EB} = -6V
Collector Emitter Cutoff Current	I _{CES}	-	-	-100	nA	V _{CES} = -32V
		300	480	-	-	I _C = -10mA, V _{CE} = -2V
		300	450	-	-	$I_C = -100 \text{mA}, V_{CE} = -2 \text{V}$
Static Forward Current Transfer Ratio (Note 10)	h _{FE}	180	290	90 - Ic = -1A, Vc= = -2V	$I_{C} = -1A, V_{CE} = -2V$	
		60	130	-	-	$I_C = -1.5A$, $V_{CE} = -2V$
		12	22	-	-	$I_C = -3A$, $V_{CE} = -2V$
		-	-25	-40		I _C =- 0.1A, I _B = -10mA
		-	-150	-220		$I_C = -1A$, $I_B = -50mA$
Collector-Emitter Saturation Voltage (Note 10)	$V_{CE(sat)}$	-	-195	-300	mV	$I_C = -1.5A$, $I_B = -100mA$
		-	-210	-300		$I_C = -2A$, $I_B = -200mA$
		-	-260	-370		$I_C = -2.5A$, $I_B = -250mA$
Base-Emitter Turn-On Voltage (Note 10)	V _{BE(on)}	-	-0.89	-0.95	V	I _C = -2.5A, V _{CE} = -2V
Base-Emitter Saturation Voltage (Note 10)	V _{BE(sat)}	-	-0.97	-1.05	V	$I_C = -2.5A$, $I_B = -250mA$
Output Capacitance	C _{obo}	-	19	25	pF	V _{CB} = -10V. f = 1MHz
Transition Frequency	f _T	150	190	-	MHz	V _{CE} = -10V, I _C = -50mA, f = 100MHz
Turn-on Time	ton	-	40	-	ns	$V_{CC} = -15V, I_C = -0.75A$
Turn-off Time	t _{off}	-	435	-	ns	$I_{B1} = I_{B2} = -15mA$

Notes: 10. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%



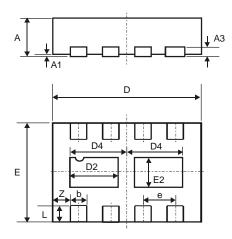
Typical Electrical Characteristics





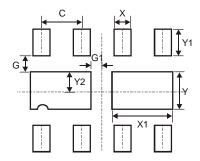


Package Outline Dimensions



DFN3020B-8					
Dim	Min	Max	Тур		
Α	0.77	0.83	0.80		
A1	0	0.05	0.02		
А3	-	-	0.15		
b	0.25	0.35	0.30		
D	2.95	3.075	3.00		
D2	0.82	1.02	0.92		
D4	1.01	1.21	1.11		
е	-	-	0.65		
Е	1.95	2.075	2.00		
E2	0.43	0.63	0.53		
L	0.25	0.35	0.30		
Z	-	-	0.375		
All	All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)		
С	0.650		
G	0.285		
G1	0.090		
Х	0.400		
X1	1.120		
Y	0.730		
Y1	0.500		
Y2	0.365		





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